



## Hydrosoluble Flux

# FLUX TYPE H35M

**H35M** Flux is a mildly active, low halide hydrosoluble flux for use in flow soldering equipment for the production of printed circuit boards. This mild hydrosoluble flux is more effective than rosin based flux in removing oxides from the surfaces to be soldered particularly in the case of bare copper.

- Non rosinous, organic acid activated flux soluble in water or alcohol
- Equivalent to rosin RMA type flux
- Meets standards NFC 90550, Din 8511 and 8516

### Physiochemical Characteristics:

- Solution : Alcoholised
- Colouration : Clear
- Density at 20°C : 1.050 +/- 0.2 at 20C
- Water washing : Highly soluble
- Alcohol washing : Very soluble
- Flash point : 21°C
- Chlorine rate : 0.005%
- Acidity : IA = 120

### Miscellaneous:

**Health and Safety:** Use in a well ventilated area away from any source of flame or ignition (COSHH sheet available).

**Packaging:** Throwaway 10litres plastic containers.

**Storage:** In original hermetically sealed containers, stored at an ideal temperature of around 20°C for 12 months.

### Application Notes:

**H35M** can be used for foam fluxing in all types of automatic flow soldering machines. Due to its concentration, the flux assists in reducing the formation of icicles, craters and facilitates good capillary rise in metalised plated through holes. Preheat temperature after fluxing should be between 80° and 90°C to give good levels of activation.

**H35M** residue must be removed after soldering by washing in either water or alcohol base cleaning materials.

Maintenance of the flux density is achieved by adding dilutant **D305**.

Shake well before use ensuring a homogeneous mix of flux is available for application